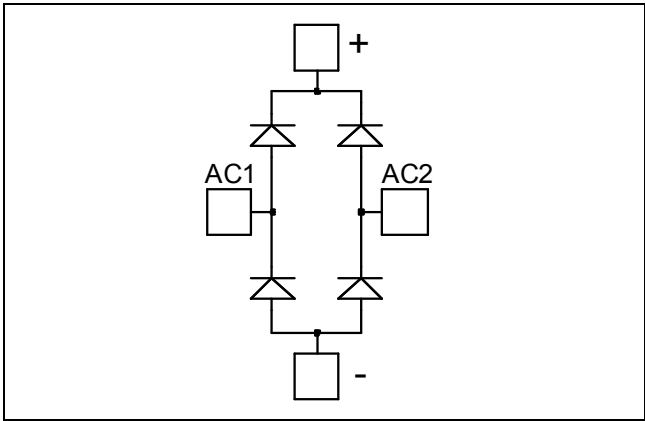


## Diode Full Bridge Power Module

**$V_{RRM} = 1700V$**   
 **$I_C = 100A @ T_c = 55^\circ C$**

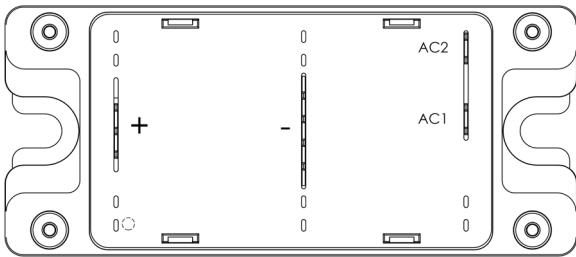


### Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- High level of integration



### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

**All ratings @  $T_j = 25^\circ C$  unless otherwise specified**

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_R$	Maximum DC reverse Voltage	1700	V
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	A
		$T_c = 25^\circ C$	
		$T_c = 55^\circ C$	100
$I_{F(RMS)}$	RMS Forward Current	125	
$I_{FSM}$	Non-Repetitive Forward Surge Current	$T_j = 25^\circ C$	300

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

## Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 100A	T <sub>j</sub> = 25°C		2.2	2.5	V
			T <sub>j</sub> = 125°C		2.1		
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> = 1700V	T <sub>j</sub> = 25°C			250	μA
			T <sub>j</sub> = 125°C			500	

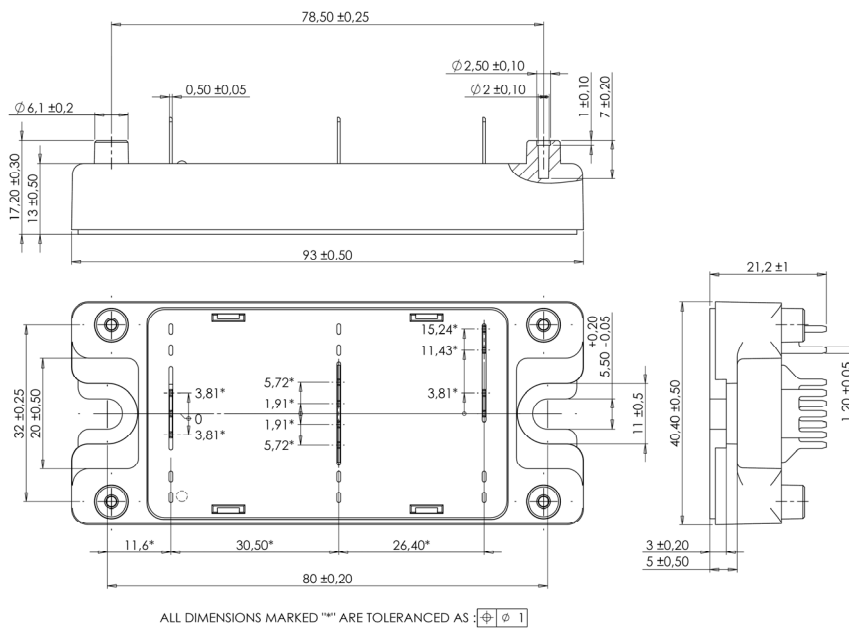
## Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 100A V <sub>R</sub> = 900V di/dt = 1000A/μs	T <sub>j</sub> = 25°C		572		ns
			T <sub>j</sub> = 125°C		704		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 100A V <sub>R</sub> = 900V di/dt = 1000A/μs	T <sub>j</sub> = 25°C		20		μC
			T <sub>j</sub> = 125°C		35		
I <sub>RRM</sub>	Reverse Recovery Current	I <sub>F</sub> = 100A V <sub>R</sub> = 900V di/dt = 1000A/μs	T <sub>j</sub> = 25°C		70		A
			T <sub>j</sub> = 125°C		100		

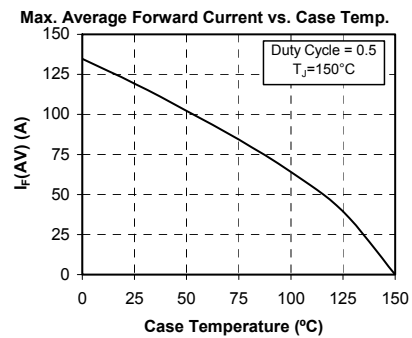
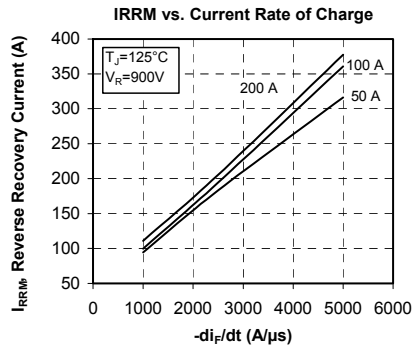
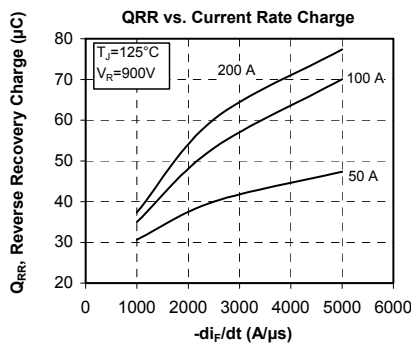
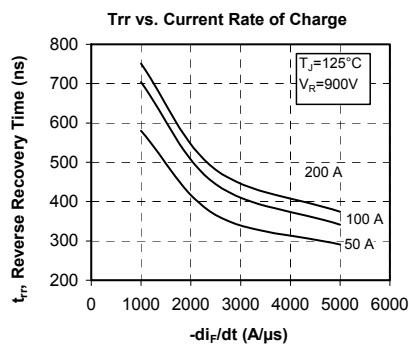
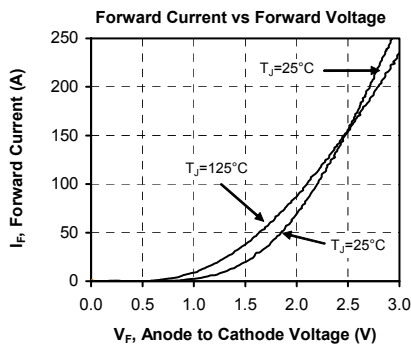
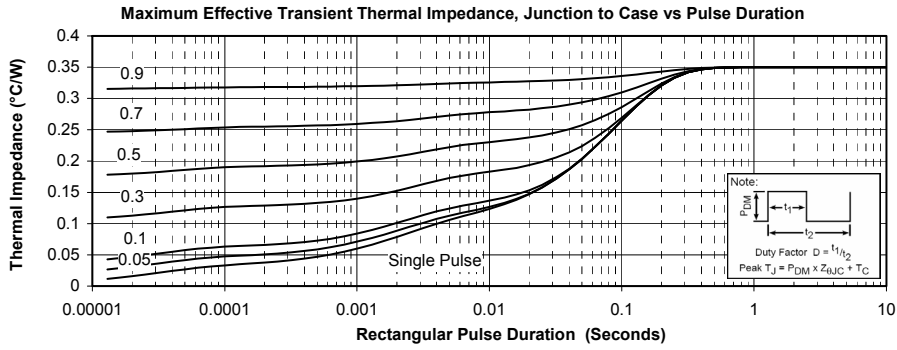
## Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.35	°C/W
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T <sub>J</sub>	Operating junction temperature range			-40		150	°C
T <sub>STG</sub>	Storage Temperature Range			-40		125	
T <sub>C</sub>	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

## SP4 Package outline (dimensions in mm)



## Typical Performance Curve



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